

Title (en)

METHOD FOR PREVENTING MOLD FORMATION BY USING HYDROPHOBIC MATERIALS, AND MOLD-CONTROLLING AGENT FOR BUILDING PARTS

Title (de)

VERFAHREN ZUR UNTERDRÜCKUNG VON SCHIMMELBILDUNG UNTER VERWENDUNG HYDROPHOBER STOFFE SOWIE EIN SCHIMMELPILZHEMMENDES MITTEL FÜR GEBÄUDETEILE

Title (fr)

PROCEDE PERMETTANT D'EMPECHER LA FORMATION DE MOISSURES AU MOYEN DE SUBSTANCES HYDROPHOBES, ET AGENT ANTI-MOISSURES POUR PARTIES DE BATIMENT

Publication

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Application

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Abstract (en)

[origin: WO2004086867A1] The invention relates to a method for preventing mold formation on building parts by using hydrophobic materials. Said method is characterized by the fact that a dispersion of hydrophobic particles having an average diameter of 0.005 to 5 µm is applied in an organic dispersing agent to the surface that is to be protected from mold formation, whereupon the dispersing agent is removed. Also disclosed is a mold growth-inhibiting agent for building parts, which is provided with 0.1 to 10 percent by weight of dispersed hydrophobic particles having an average diameter of 0.005 to 5 µm in an organic dispersing agent.

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